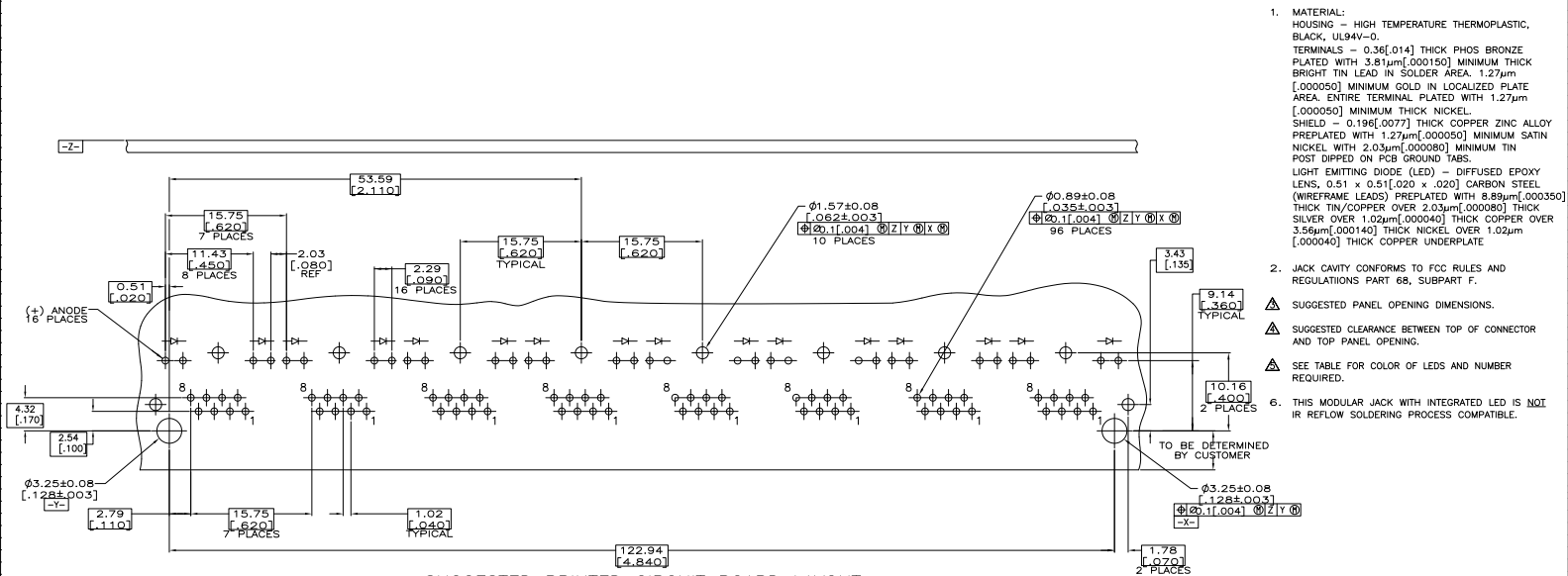
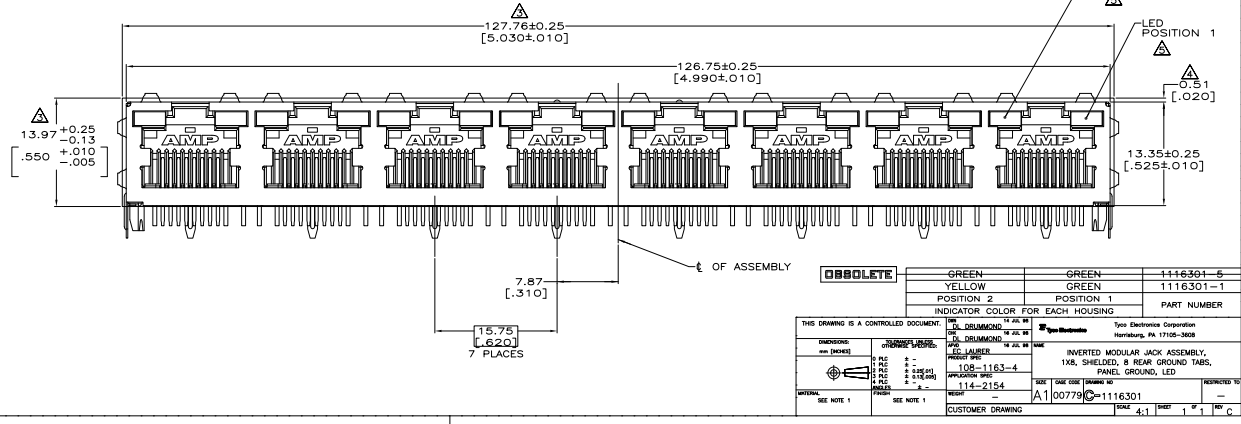
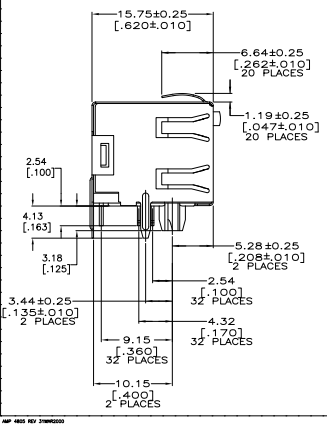


REV	DATE	DESCRIPTION	BY	CHK
AA	00			
C		ECO-08-00030	ORANOR	LAM/JW



SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
 (COMPONENT SIDE)



- MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK BRIGHT TIN LEAD IN SOLDER AREA. 1.27µm [0.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [0.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[0.000050] MINIMUM SATIN NICKEL WITH 2.03µm[0.000080] THICK TIN/COPPER OVER 2.03µm[0.000080] THICK SILVER OVER 1.02µm[0.000040] THICK COPPER OVER 3.56µm[0.00140] THICK NICKEL OVER 1.02µm [0.000040] THICK COPPER UNDERPLATE.
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- SUGGESTED PANEL OPENING DIMENSIONS.
- SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IN REFLOW SOLDERING PROCESS COMPATIBLE.

OBsolete		GREEN	GREEN	11-16301-6
		YELLOW	GREEN	1116301-1
		POSITION 2	POSITION 1	PART NUMBER
		INDICATOR COLOR FOR EACH HOUSING		
THIS DRAWING IS A CONTROLLED DOCUMENT		TYS Electronics Corporation Harrisburg, PA 17105-3608		
INCHES	MILLIMETERS	DATE	REV	BY
108-1163-4	114-2154	11-16301	1	1
CUSTOMER DRAWING		DATE	REV	BY
		11-16301	1	1